TEXAS INSTRUMENTS
SN65LVDS93B
JAJSF06A – MARCH 2018 – REVISED MAY 2018

SN65LVDS93B 10MHz～85MHz 28ビットFlat Panel Display Link LVDS Serdesトランスミッタ

1 特長

- 工業用温度範囲: －40℃～85℃
- LVDS内蔵LCDパネルに直接接続できるLVDSディスプレイSerDesインターフェイス
- パッケージ・オプション: 8.1mm×14mm TSSOP
- 1.8V～3.3V対応のデータ入力により、低消費電力、低電圧のアプリケーションおよびグラフィック・プロセッサへの直接接続が可能
- 最高85Mppsの転送レート、ピクセル・クロック周波数範囲: 10MHz～85MHz、最高2.38Gbpsのデータレートに対応
- 低EMIでHVGAからHDまでのディスプレイ解像度に最適
- 単一の3.3V電源で動作し、75MHzで170mW (標準値)
- 28データ・チャネル＋クロック入力(低電圧TTL)から、4データ・チャネル＋クロック出力(低電圧差動)
- ディセーブル時の消費電力: 1mW未満
- 立ち上がりまたは立ち下がりクロック・エッジによる入力トリガを選択可能
- ESD: 5kV HBM
- スペクトラム拡散クロック(SSC)に対応
- RGB 888によるLVDS I変換をサポート

2 アプリケーション

- HMIパネル(ヒューマン・マシン・インターフェイス)
- 産業用PCディスプレイ
- 医療用画像ディスプレイ
- LCDディスプレイ・パネル・ドライバ

3 概要

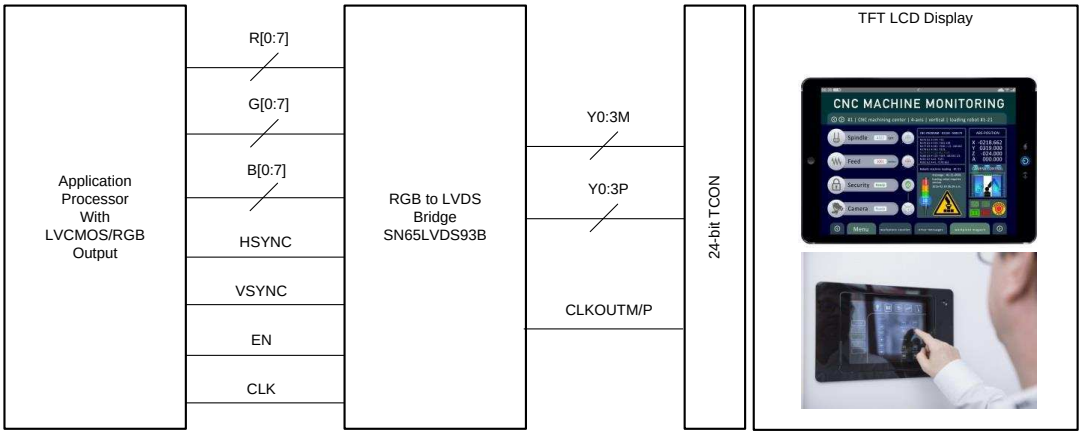
SN65LVDS93B LVDS SerDes (シリアライザ/デシリアライザ)トランスミッタは、単一の集積回路に4つの7ビット・パラレル・ロード/シリアル出力シフト・レジスタ、1つの7Xクロック・シンセサイザ、5つの低電圧差動信号(LVDS)ドライバを搭載しています。これらの機能により、5つの平衡対導体を介して28ビットのシングルエンドLVTTLデータを同期伝送して、DS90CR286AおよびSN65LVDS94などの対応レシーバで受信することができます。

製品情報(1)

型番	パッケージ	本体サイズ(公称)
SN65LVDS93B	TSSOP (56)	14.00mm×6.10mm

(1) 利用可能なすべてのパッケージについては、このデータシートの末尾にある注文情報を参照してください。

ディスクリートLVDS TXを使用するRGBビデオ・システム



目次

4 改訂履歴

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

2018年3月発行のものから更新 **Page**

- デバイスのステータスを「*事前情報*」から「*量産データ*」に変更 ... 1

5 概要（続き）

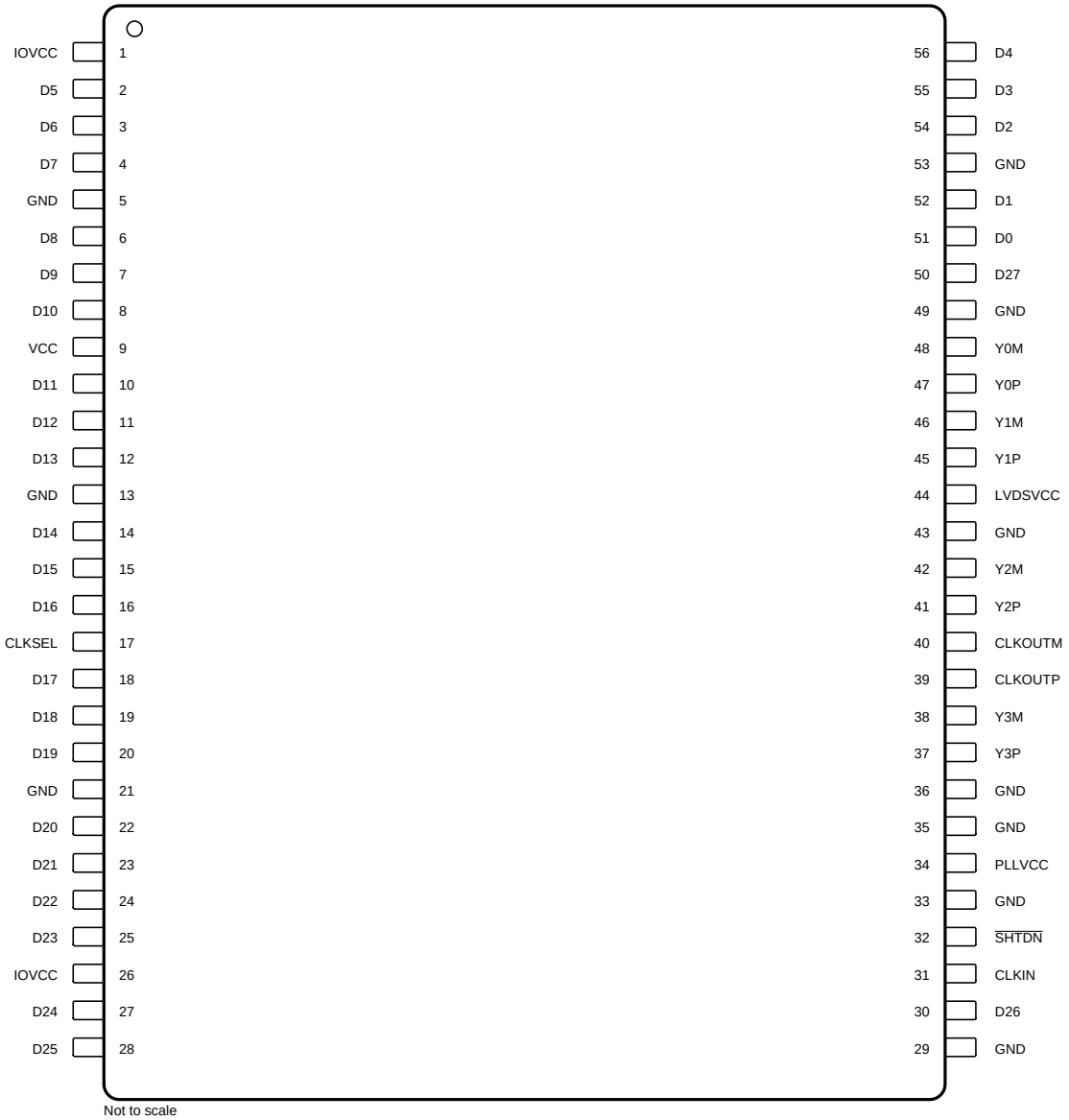
送信時には、入力クロック信号(CLKIN)のエッジで、データ・ビットD0～D27がそれぞれレジスタにロードされます。クロックの立ち上がり/立ち下がりエッジは、クロック選択(CLKSEL)ピンで選択できます。CLKINの周波数を7倍にし、これを用いてデータ・レジスタを7ビット・スライスで直列にアンロードします。これにより、4つのシリアル・ストリームと位相ロックされたクロック(CLKOUT)がLVDS出力ドライバに出力されます。CLKOUTの周波数は入力クロックCLKINと同じです。

SN65LVDS93Bは外付け部品が不要で、制御もほとんどまたは全く必要ありません。トランスミッタへの入力時とレシーバの出力時のデータ・バスは同じになり、ユーザーが意識することなくデータを伝送できます。ユーザーによる操作は、CLKSELにHIGHレベルを入力してクロック立ち上がりエッジを選択したり、LOWレベル入力で立ち下がりエッジを選択するほか、シャットダウン/クリア(SHTDN)信号を使用するくらいです。SHTDNはアクティブLOW入力であり、クロックを抑止してLVDS出力ドライバをシャットオフすることにより、消費電力を削減できます。この信号がLOWレベルになると、すべての内部レジスタはクリアされてLOWレベルになります。

SN65LVDS93Bは周囲温度範囲－40℃～85℃で動作するよう仕様が規定されています。

6 Pin Configuration and Functions

DGG Package
56-Pin TSSOP
(Top View)



Not to scale

Pin Functions

PIN		I/O	DESCRIPTION
NAME	NO.		
CLKSEL	17	I	Selects between rising edge input clock trigger (CLKSEL = V_{IH}) and falling edge input clock trigger (CLKSEL = V_{IL}).
CLKIN	31	I	Input pixel clock; rising or falling clock polarity is selectable by Control input CLKSEL.
CLKOUTM	40	O	Differential LVDS pixel clock output. Output is high-impedance when $\overline{SHTDN}$ is pulled low (de-asserted).
CLKOUTP	39	O	
D0	51	I	Data inputs; supports 1.8-V to 3.3-V input voltage selectable by VDD supply. To connect a graphic source successfully to a display, the bit assignment of D[27:0] is critical (and not necessarily intuitive). Note: if application only requires 18-bit color, connect unused inputs D5, D10, D11, D16, D17, D23, and D27 to GND
D1	52		
D2	54		
D3	55		
D4	56		
D5	2		
D6	3		
D7	4		
D8	6		
D9	7		
D10	8		
D11	10		
D12	11		
D13	12		
D14	14		
D15	15		
D16	16		
D17	18		
D18	19		
D19	20		
D20	22		
D21	23		
D22	24		
D23	25		
D24	27		
D25	28		
D26	30		
D27	50		
GND	5, 13, 21, 29, 33, 35, 36, 43, 49, 53	Power Supply(1)	Supply Ground for VCC, IOVCC, LVDSVCC, and PLLVCC.
IOVCC	1, 26		I/O supply reference voltage (1.8 V up to 3.3 V matching the GPU data output signal swing)
LVDSVCC	44		3.3-V LVDS output analog supply
PLLVCC	34		3.3-V PLL analog supply
$\overline{SHTDN}$	32	I	Device shut down; pull low (de-assert) to shut down the device (low power, resets all registers) and high (assert) for normal operation.
VCC	9	Power Supply(1)	3.3-V digital supply voltage
Y0M	48	O	Differential LVDS data outputs. Outputs are high-impedance when $\overline{SHTDN}$ is pulled low (de-asserted)
Y1M	46		
Y2M	42		
Y0P	47		
Y1P	45		
Y2P	41		
Y3M	38	O	Differential LVDS Data outputs. Output is high-impedance when $\overline{SHTDN}$ is pulled low (de-asserted). Note: if the application only requires 18-bit color, this output can be left open.
Y3P	37		

(1) For a multilayer pcb, TI recommends keeping one common GND layer underneath the device and connecting all ground terminals directly to this plane.

7 Specifications

7.1 Absolute Maximum Ratings(1)

	MIN	MAX	UNIT
Supply voltage, VCC, IOVCC, LVDSVCC, PLLVCC(2)	–0.5	4	V
Voltage at any output terminal	–0.5	VCC + 0.5	V
Voltage at any input terminal	–0.5	IOVCC + 0.5	V
Continuous power dissipation	See *Thermal Information*		
Storage temperature, T_{stg}	–65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device.Theseare stress ratings only, which do not imply functional operation of the device at these oranyother conditions beyond those indicated under *RecommendedOperatingConditions*. Exposure to absolute-maximum-rated conditions for extended periodsmayaffect device reliability.
(2) All voltages are with respect to the GND terminals.

7.2 ESD Ratings

		VALUE	UNIT
$V_{(ESD)}$ Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001(1)	± 5000	V
	Charged-device model (CDM), per JEDEC specification JESD22-C101(2)	± 1500	

(1) JEDEC document JEP155 states that 500-V HBM allowssafemanufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allowssafemanufacturing with a standard ESD control process.

7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

PARAMETER		MIN	NOM	MAX	UNIT
Supply voltage, VCC		3	3.3	3.6	V
LVDS output supply voltage, LVDSVCC		3	3.3	3.6	
PLL analog supply voltage, PLLVCC		3	3.3	3.6	
IO input reference supply voltage, IOVCC		1.62	1.8 / 2.5 / 3.3	3.6	
Power supply noise on any VCC terminal				0.1	
High-level input voltage, V_{IH}	IOVCC = 1.8 V	IOVCC/2 + 0.3 V			V
	IOVCC = 2.5 V	IOVCC/2 + 0.4 V			
	IOVCC = 3.3 V	IOVCC/2 + 0.5 V			
Low-level input voltage, V_{IL}	IOVCC = 1.8 V			IOVCC/2 – 0.3 V	V
	IOVCC = 2.5 V			IOVCC/2 – 0.4 V	
	IOVCC = 3.3 V			IOVCC/2 – 0.5 V	
Differential load impedance, Z_L		90		132	Ω
Operating free-air temperature, T_A		–45		85	°C

7.4 Thermal Information

THERMAL METRIC(1)		SN65LVDS93B DGG (TSSOP) 56 PINS	UNIT
$R_{\theta JA}$	Junction-to-ambient thermal resistance	62.1	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	18.4	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	31.1	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	0.8	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	30.8	°C/W

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

7.5 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_T	Input voltage threshold	R_L = 100 Ω, See 図 5		IOVCC/2		V
$\|V_{OD}\|$	Differential steady-state output voltage magnitude		250		450	mV
$\Delta\|V_{OD}\|$	Change in the steady-state differential output voltage magnitude between opposite binary states			1	35	mV
$V_{OC(SS)}$	Steady-state common-mode output voltage	See 図 5 $t_{R/F}$ (Dx, CLKin) = 1 ns	1.125		1.375	V
$V_{OC(PP)}$	Peak-to-peak common-mode output voltage				35	mV
I_{IH}	High-level input current	V_{IH} = IOVCC			25	µA
I_{IL}	Low-level input current	V_{IL} = 0 V			±10	µA
I_{OS}	Short-circuit output current	V_{OY} = 0 V			±24	mA
		V_{OD} = 0 V			±12	mA
I_{OZ}	High-impedance state output current	V_O = 0 V to VCC			±20	µA
R_{pdn}	Input pulldown integrated resistor on all inputs (Dx, CLKSEL, $\overline{SHTDN}$, CLKIN)	IOVCC = 1.8 V		200		kΩ
		IOVCC = 3.3 V		100		
I_Q	Quiescent current	Disabled, all inputs at GND; $\overline{SHTDN}$ = V_{IL}		10	100	µA
I_{CC}	Supply current (average)	$\overline{SHTDN}$ = V_{IH}, R_L = 100 Ω (5 places), grayscale pattern (図 6) VCC = 3.3 V, f_{CLK} = 75 MHz				
		$I_{(VCC)}$ + $I_{(PLLVCC)}$ + $I_{(LVDSVCC)}$		51.9		mA
		$I_{(IOVCC)}$ with IOVCC = 3.3 V		0.4		
		$I_{(IOVCC)}$ with IOVCC = 1.8 V		0.1		
		$\overline{SHTDN}$ = V_{IH}, R_L = 100 Ω (5 places), worst-case pattern (図 7), VCC = 3.6 V, f_{CLK} = 75 MHz				
		$I_{(VCC)}$ + $I_{(PLLVCC)}$ + $I_{(LVDSVCC)}$		63.7		mA
		$I_{(IOVCC)}$ with IOVCC = 3.3 V		1.3		
		$I_{(IOVCC)}$ with IOVCC = 1.8 V		0.5		
		$\overline{SHTDN}$ = V_{IH}, R_L = 100 Ω (5 places), worst-case pattern (図 7), f_{CLK} = 85 MHz				
		$I_{(VCC)}$ + $I_{(PLLVCC)}$ + $I_{(LVDSVCC)}$		75.1		mA
		$I_{(IOVCC)}$ with IOVCC = 3.6 V		1.5		
		$I_{(IOVCC)}$ with IOVCC = 1.8 V		0.6		
C_I	Input capacitance			2		pF

7.6 Timing Requirements

		MIN	MAX	UNIT
Input clock period, t_c		7.4	100	ns
Input clock modulation	w/ modulation frequency 30 kHz		8%	
	w/ modulation frequency 50 kHz		6%	
High-level input clock pulse width duration, t_w		0.4 t_c	0.6 t_c	ns
Input signal transition time, t_t			3	ns
Data set up time, D0 through D27 before CLKIN (See 図 4)		2		ns
Data hold time, D0 through D27 after CLKIN		0.8		ns

7.7 Switching Characteristics

over operating free-air temperature range (unless otherwise noted)

		TEST CONDITIONS	MIN	TYP(1)	MAX	UNIT
t_0	Delay time, CLKOUT↑ after Yn valid (serial bit position 0, equal D1, D9, D20, D5)	See 図 8, t_C = 10 ns, |Input clock jitter| < 25 ps (2)	–0.1	0	0.1	ns
t_1	Delay time, CLKOUT↑ after Yn valid (serial bit position 1, equal D0, D8, D19, D27)		$^1/_7\ t_c$ – 0.1		$^1/_7\ t_c$ + 0.1	ns
t_2	Delay time, CLKOUT↑ after Yn valid (serial bit position 2, equal D7, D18, D26. D23)		$^2/_7\ t_c$ – 0.1		$^2/_7\ t_c$ + 0.1	ns
t_3	Delay time, CLKOUT↑ after Yn valid (serial bit position 3; equal D6, D15, D25, D17)		$^3/_7\ t_c$ – 0.1		$^3/_7\ t_c$ + 0.1	ns
t_4	Delay time, CLKOUT↑ after Yn valid (serial bit position 4, equal D4, D14, D24, D16)		$^4/_7\ t_c$ – 0.1		$^4/_7\ t_c$ + 0.1	ns
t_5	Delay time, CLKOUT↑ after Yn valid (serial bit position 5, equal D3, D13, D22, D11)		$^5/_7\ t_c$ – 0.1		$^5/_7\ t_c$ + 0.1	ns
t_6	Delay time, CLKOUT↑ after Yn valid (serial bit position 6, equal D2, D12, D21, D10)		$^6/_7\ t_c$ – 0.1		$^6/_7\ t_c$ + 0.1	ns
$t_{c(o)}$	Output clock period			t_c		ns
$\Delta t_{c(o)}$	Output clock cycle-to-cycle jitter (3)	t_C = 10 ns; clean reference clock, see 図 9		±35		ps
		t_C = 10 ns with 0.05UI added noise modulated at 3 MHz, see 図 9		±44		
		t_C = 7.4 ns; clean reference clock, see 図 9		±35		
		t_C = 7.4 ns with 0.05UI added noise modulated at 3 MHz, see 図 9		±42		
t_w	High-level output clock pulse duration			$^4/_7\ t_c$		ns
$t_{r/f}$	Differential output voltage transition time (t_r or t_f)	See 図 5		225	500	ps
t_{en}	Enable time, $\overline{SHTDN}$↑ to phase lock (Yn valid)	$f_{(clk)}$ = 85 MHz, See 図 10		10		µs
t_{dis}	Disable time, $\overline{SHTDN}$↓ to off-state (CLKOUT high-impedance)	$f_{(clk)}$ = 85 MHz, See 図 11		12		ns

(1) All typical values are at V_{CC} = 3.3V,T_A = 25°C.
(2) |Input clock jitter| is the magnitude of the change in theinputclock period.
(3) The output clock cycle-to-cycle jitter is the largestrecordedchange in the output clock period from one cycle to the next cycle observed over15,000cycles.Tektronix TDSJIT3 Jitter Analysis software was used to derive the maximum and minimumjittervalue.

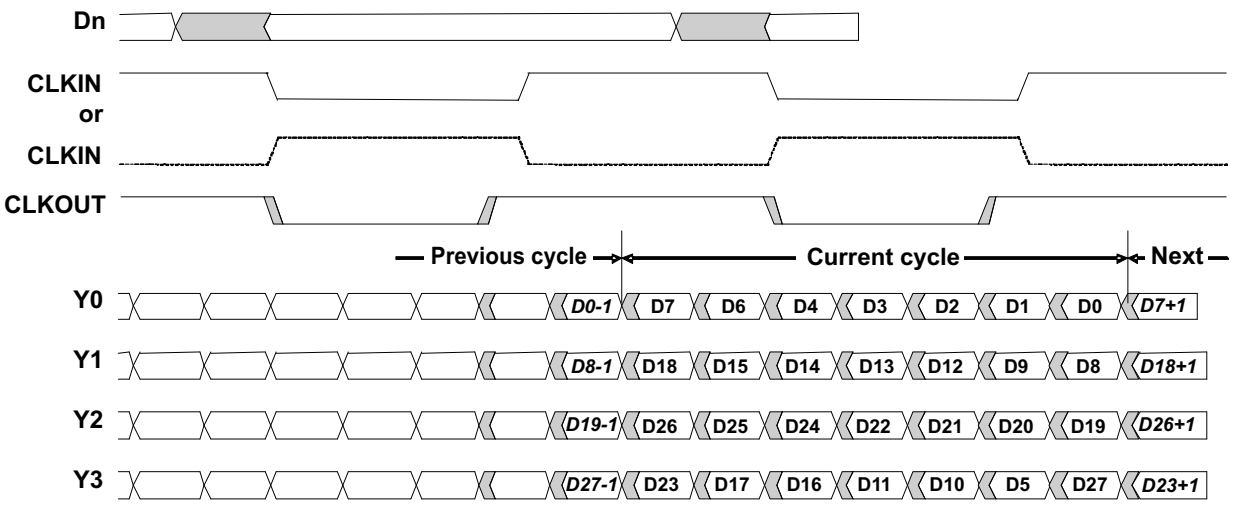
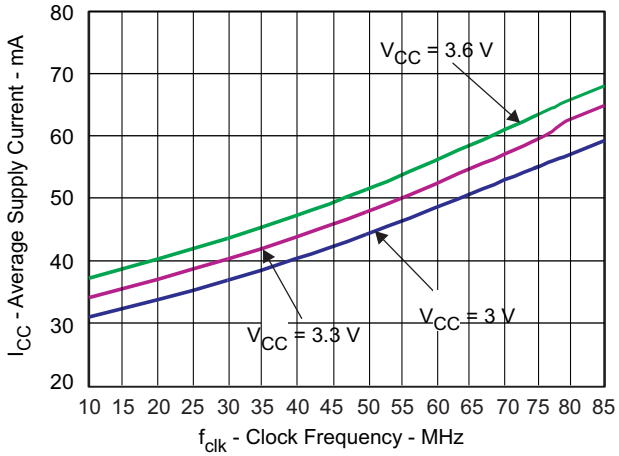


図 1. Typical SN65LVDS93B Load and Shift Sequences

7.8 Typical Characteristics



Total device current (using grayscale pattern) over pixel clock frequency

図 2. Average Grayscale ICC vs Clock Frequency

8 Parameter Measurement Information

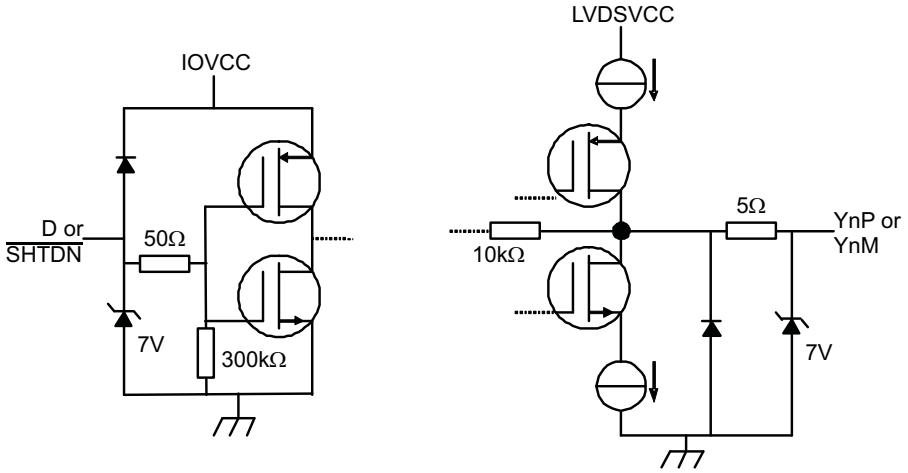
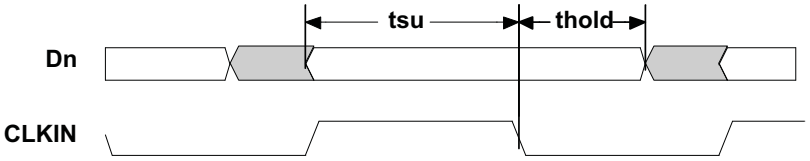


図 3. Equivalent Input and Output Schematic Diagrams



All input timing is defined at IOVDD / 2 on an input signal with a 10% to 90% rise or fall time of less than 3 ns. CLKSEL = 0V.

図 4. Setup and Hold Time Definition

Parameter Measurement Information (continued)

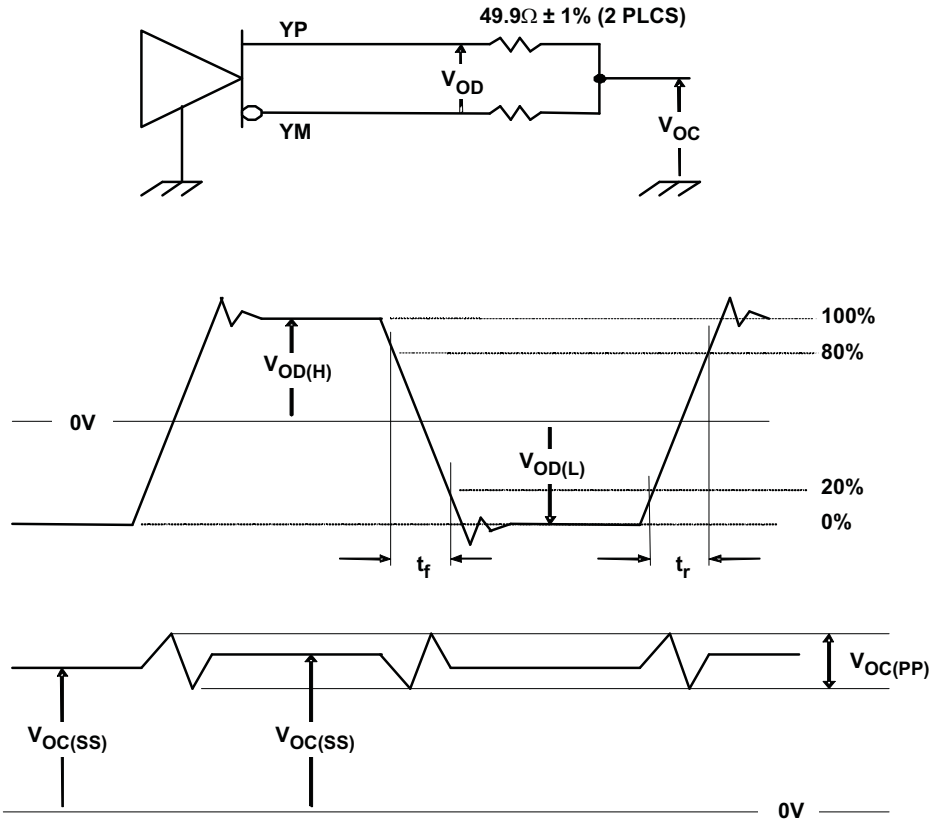
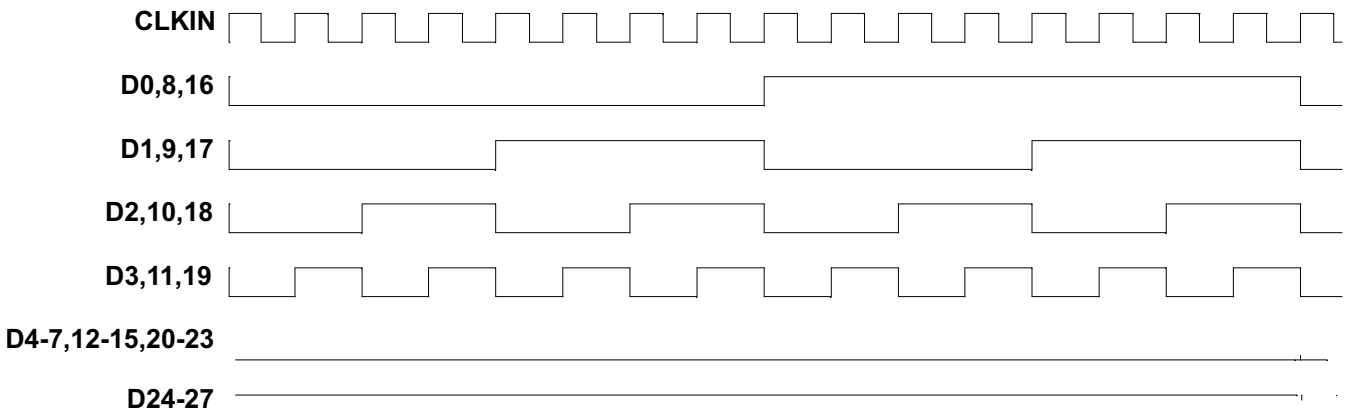


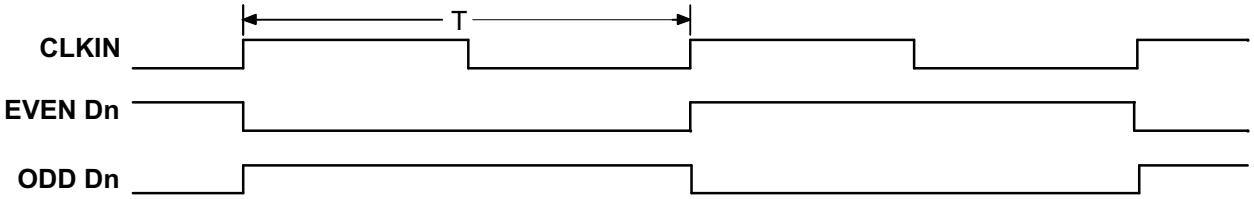
図 5. Test Load and Voltage Definitions for LVDS Outputs



The 16 grayscale test pattern test device power consumption for a typical display pattern.

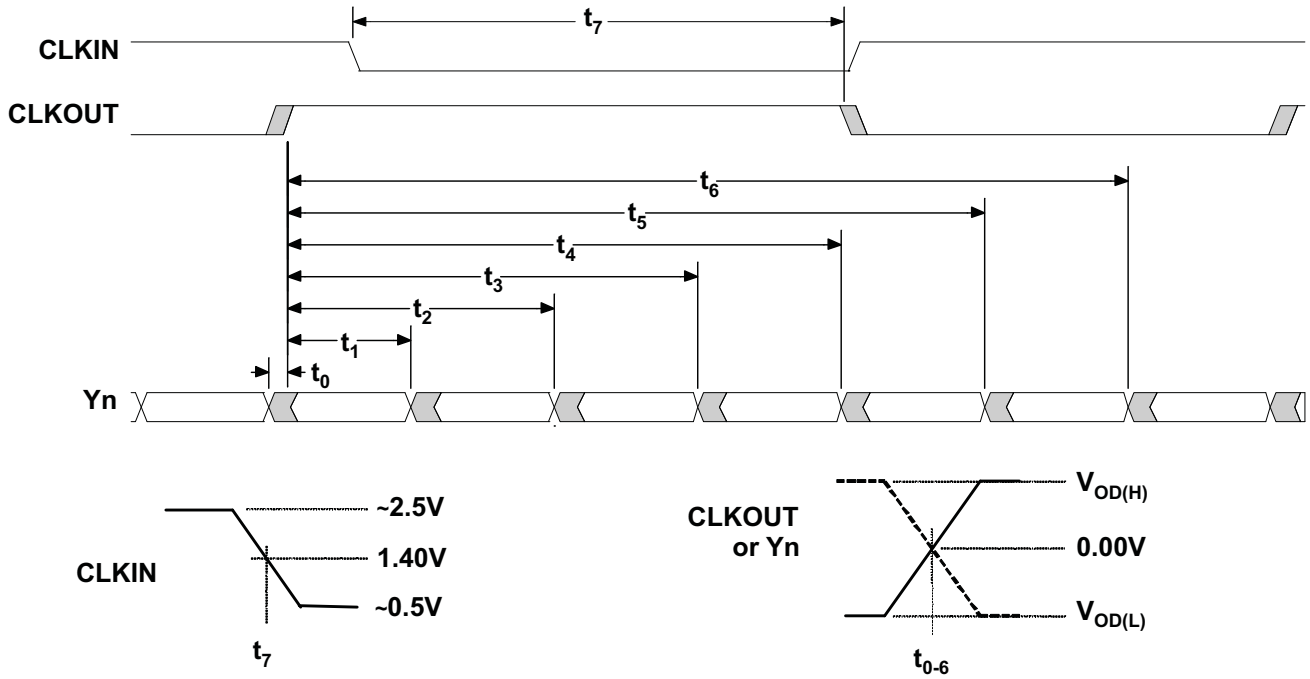
図 6. 16 Grayscale Test Pattern

Parameter Measurement Information (continued)



The worst-case test pattern produces nearly the maximum switching frequency for all of the LVDS outputs.

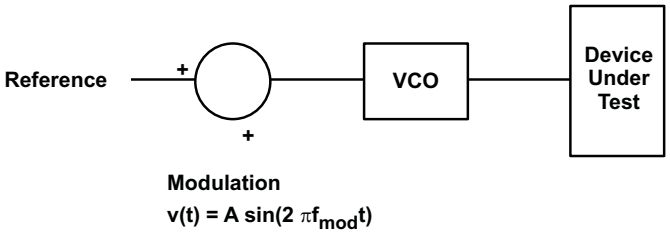
図 7. Worst-Case Power Test Pattern



CLKOUT is shown with CLKSEL at high-level.
CLKIN polarity depends on CLKSEL input level.

図 8. SN65LVDS93B Timing Definitions

Parameter Measurement Information (continued)



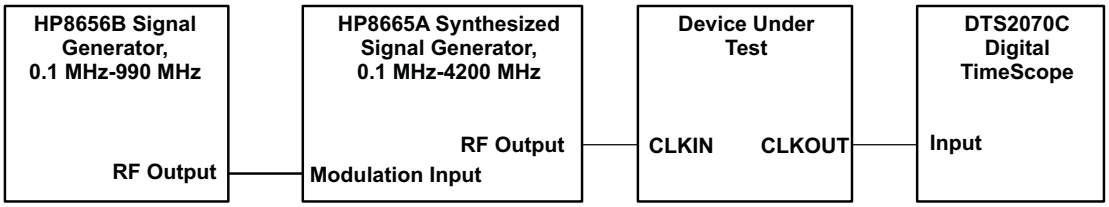


図 9. Output Clock Jitter Test Set Up

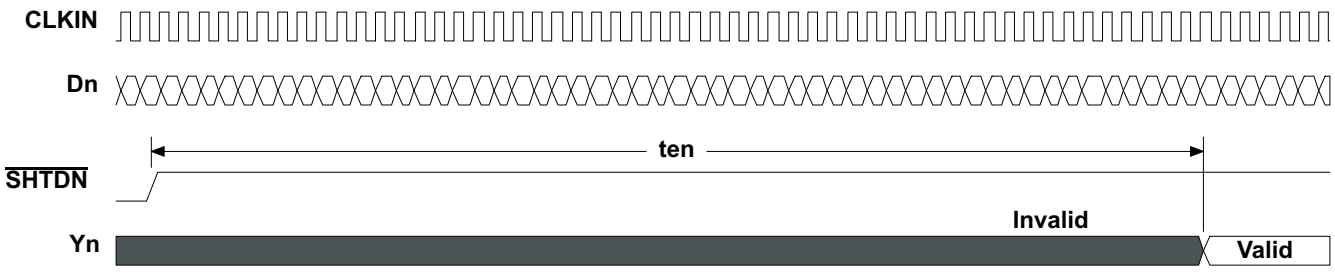


図 10. Enable Time Waveforms

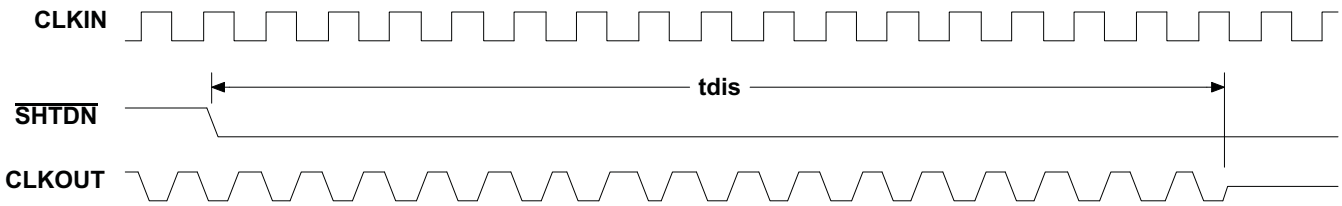


図 11. Disable Time Waveforms

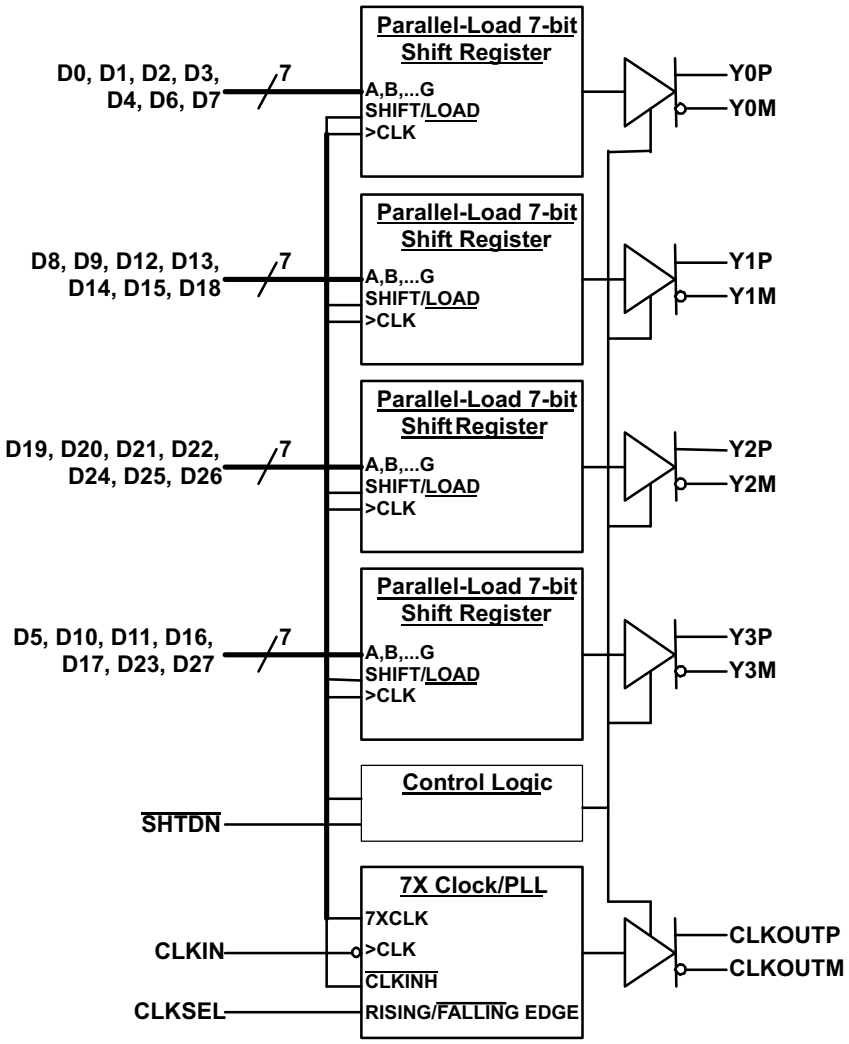
9 Detailed Description

9.1 Overview

The SN65LVDS93B takes in three (or four) data words each containing seven single-ended data bits, and converts this to an LVDS serial output. Each serial output runs at seven times that of the parallel data rate. The deserializer (receiver) device operates in the reverse manner. The three (or four) LVDS serial inputs are transformed back to the original 7-bit parallel single-ended data. Additional TI solutions are available in 21:3 or 28:4 SerDes ratios.

- The 21-bit devices are designed for 6-bit RGB video for a total of 18 bits in addition to 3 extra bits for horizontal synchronization, vertical synchronization, and data enable.
- The 28-bit devices are intended for 8-bit RGB video applications. Again, the extra 4 bits are for horizontal synchronization, vertical synchronization, data enable, and the remaining is the reserved bit. These 28-bit devices can also be used in 6-bit and 4-bit RGB applications as shown in the subsequent system diagrams.

9.2 Functional Block Diagram



9.3 Feature Description

9.3.1 TTL Input Data

The data inputs to the transmitter come from the graphics processor and consist of up to 24 bits of video information, a horizontal synchronization bit, a vertical synchronization bit, an enable bit, and a spare bit. The data can be loaded into the registers upon either the rising or falling edge of the input clock selectable by the CLKSEL pin. Data inputs are 1.8 V to 3.3 V tolerant for the SN65LVDS93B and can connect directly to low-power, low-voltage application and graphic processors. The bit mapping is listed in 表 1.

表 1. Pixel Bit Ordering

	RED	GREEN	BLUE
LSB	R0	G0	B0
	R1	G1	B1
	R2	G2	B2
4-bit MSB	R3	G3	B3
	R4	G4	B4
6-bit MSB	R5	G5	B5
	R6	G6	B6
8-bit MSB	R7	G7	B7

9.3.2 LVDS Output Data

The pixel data assignment is listed in 表 2 for 24-bit, 18-bit, and 12-bit color hosts.

表 2. Pixel Data Assignment

SERIAL CHANNEL	DATA BITS	8-BIT			6-BIT	4-BIT	
		FORMAT-1	FORMAT-2	FORMAT-3		NON-LINEAR STEP SIZE	LINEAR STEP SIZE
Y0	D0	R0	R2	R2	R0	R2	VCC
	D1	R1	R3	R3	R1	R3	GND
	D2	R2	R4	R4	R2	R0	R0
	D3	R3	R5	R5	R3	R1	R1
	D4	R4	R6	R6	R4	R2	R2
	D6	R5	R7	R7	R5	R3	R3
	D7	G0	G2	G2	G0	G2	VCC
Y1	D8	G1	G3	G3	G1	G3	GND
	D9	G2	G4	G4	G2	G0	G0
	D12	G3	G5	G5	G3	G1	G1
	D13	G4	G6	G6	G4	G2	G2
	D14	G5	G7	G7	G5	G3	G3
	D15	B0	B2	B2	B0	B2	VCC
	D18	B1	B3	B3	B1	B3	GND
Y2	D19	B2	B4	B4	B2	B0	B0
	D20	B3	B5	B5	B3	B1	B1
	D21	B4	B6	B6	B4	B2	B2
	D22	B5	B7	B7	B5	B3	B3
	D24	HSYNC	HSYNC	HSYNC	HSYNC	HSYNC	HSYNC
	D25	VSYNC	VSYNC	VSYNC	VSYNC	VSYNC	VSYNC
	D26	ENABLE	ENABLE	ENABLE	ENABLE	ENABLE	ENABLE

表 2. Pixel Data Assignment (continued)

SERIAL CHANNEL	DATA BITS	8-BIT			6-BIT	4-BIT	
		FORMAT-1	FORMAT-2	FORMAT-3		NON-LINEAR STEP SIZE	LINEAR STEP SIZE
Y3	D27	R6	R0	GND	GND	GND	GND
	D5	R7	R1	GND	GND	GND	GND
	D10	G6	G0	GND	GND	GND	GND
	D11	G7	G1	GND	GND	GND	GND
	D16	B6	B0	GND	GND	GND	GND
	D17	B7	B1	GND	GND	GND	GND
	D23	RSVD	RSVD	GND	GND	GND	GND
CLKOUT	CLKIN	CLK	CLK	CLK	CLK	CLK	CLK

9.4 Device Functional Modes

9.4.1 Input Clock Edge

The transmission of data bits D0 through D27 occurs as each are loaded into registers upon the edge of the CLKIN signal, where the rising or falling edge of the clock may be selected through CLKSEL. The selection of a clock rising edge occurs by inputting a high level to CLKSEL, which is achieved by populating pullup resistor to pull CLKSEL=high. Inputting a low level to select a clock falling edge is achieved by directly connecting CLKSEL to GND.

9.4.2 Low Power Mode

The SN65LVDS93B can be put in low-power consumption mode by active-low input SHTDN#. Connecting pin SHTDN# to GND will inhibit the clock and shut off the LVDS output drivers for lower power consumption. A low-level on this signal clears all internal registers to a low-level. Populate a pullup to VCC on SHTDN# to enable the device for normal operation.

10 Application and Implementation

注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

10.1 Application Information

This section describes the power up sequence, provides information on device connectivity to various GPU and LCD display panels, and offers a PCB routing example.

10.2 Typical Application

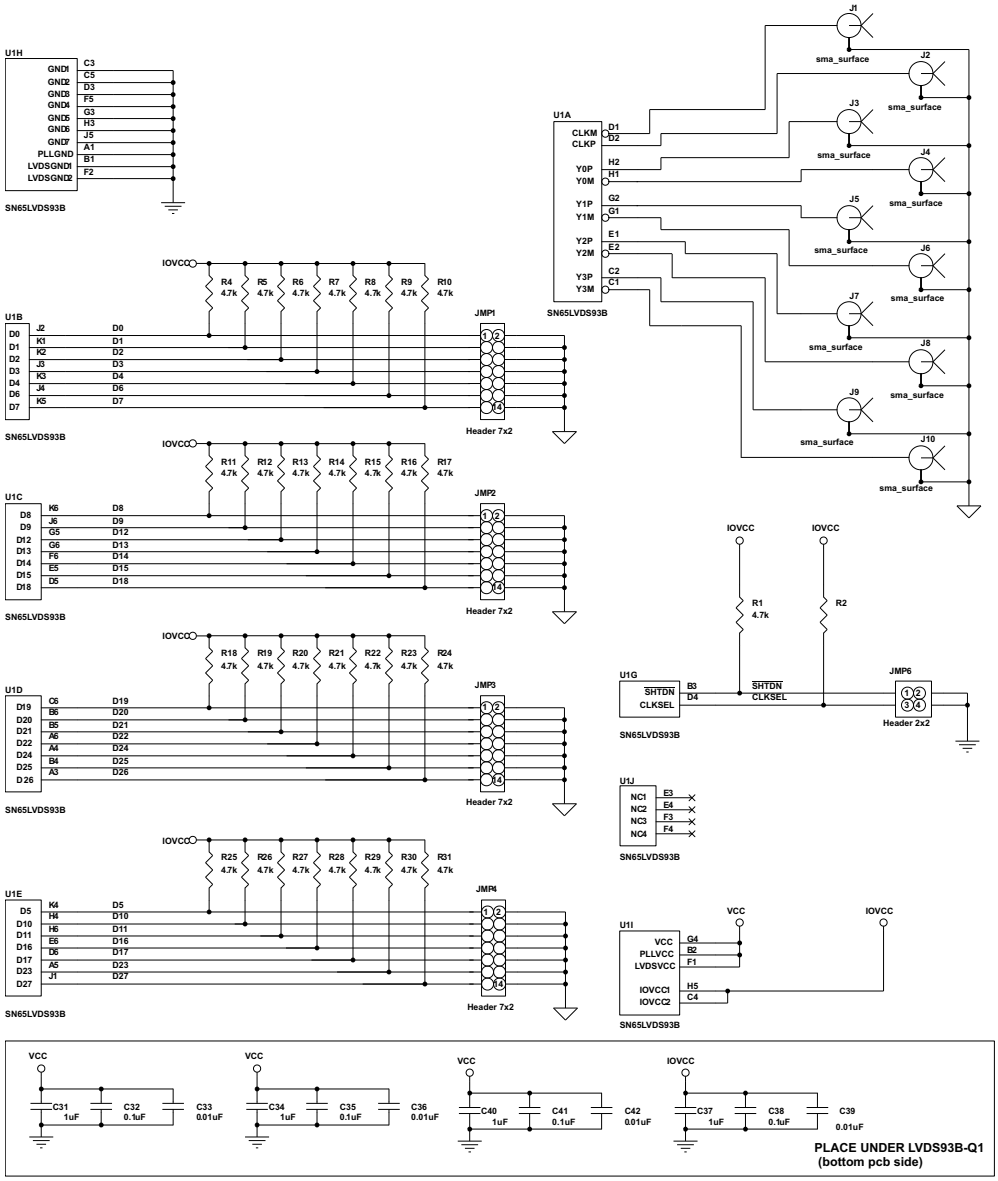


図 12. Schematic Reference

Typical Application (continued)

10.2.1 Design Requirements

For this design example, use the parameters listed in 表 3 as the input parameters.

表 3. Design Parameters

DESIGN PARAMETER	EXAMPLE VALUE
VCC	3.3 V
VCCIO	1.8 V
CLKIN	Falling edge
SHTDN#	High
Format	18-bit GPU to 24-bit LCD

10.2.2 Detailed Design Procedure

10.2.2.1 Power

The SN65LVDS93B does not require a specific power-up sequence.

The device is permitted to power up IOVCC while VCC, VCCPLL, and VCCLVDS remain powered down and connected to GND. The input level of the $\overline{\text{SHTDN}}$ during this time does not matter as only the input stage is powered up while all other device blocks are still powered down.

The device is also permitted to power up all 3.3-V power domains while IOVCC is still powered down to GND. The device will not suffer damage. However, in this case, all the I/Os are detected as logic HIGH, regardless of their true input voltage level. Hence, connecting $\overline{\text{SHTDN}}$ to GND will still be interpreted as a logic HIGH; the LVDS output stage turns on. The power consumption in this condition is significantly higher than standby mode, but still lower than normal mode.

The user experience can be impacted by the way a system powers up and powers down an LCD screen. The following sequence is recommended:

Power-up sequence (SN65LVDS93B $\overline{\text{SHTDN}}$ input initially low):

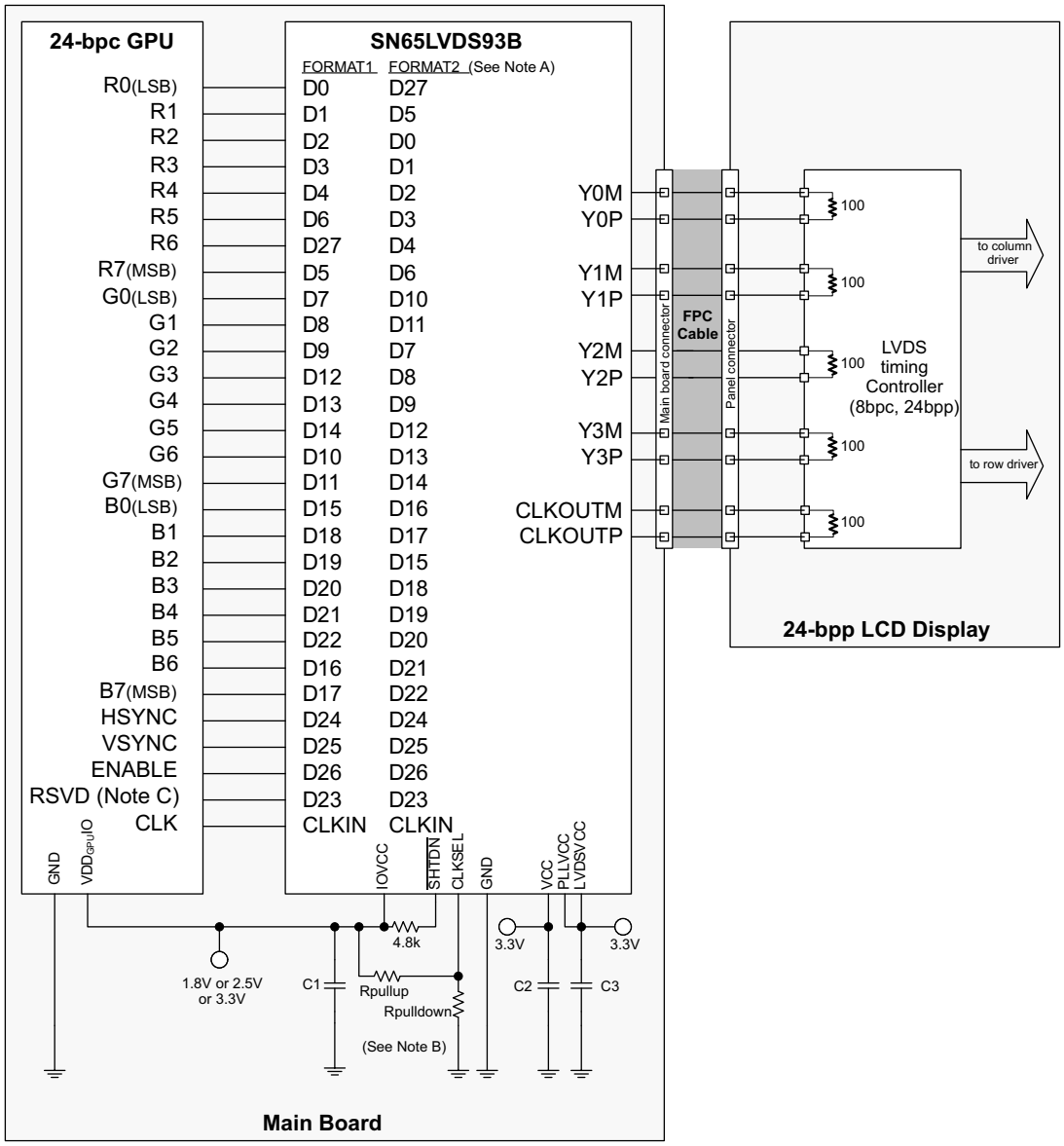
A. Ramp up LCD power (maybe 0.5 ms to 10 ms) but keep backlight turned off.
B. Wait for additional 0-200 ms to ensure display noise won't occur.
C. Enable video source output; start sending black video data.
D. Toggle SN65LVDS93B shutdown to $\overline{\text{SHTDN}} = V_{IH}$.
E. Send >1 ms of black video data; this allows the SN65LVDS93B to be phase locked, and the display to show black data first.
F. Start sending true image data.
G. Enable backlight.

Power-down sequence (SN65LVDS93B $\overline{\text{SHTDN}}$ input initially high):

A. Disable LCD backlight; wait for the minimum time specified in the LCD data sheet for the backlight to go low.
B. Video source output data switch from active video data to black image data (all visible pixel turn black); drive this for >2 frame times.
C. Set SN65LVDS93B input $\overline{\text{SHTDN}}$ = GND; wait for 250 ns.
D. Disable the video output of the video source.
E. Remove power from the LCD panel for lowest system power.

10.2.2.2 Signal Connectivity

While there is no formal industry standardized specification for the input interface of LVDS LCD panels, the industry has aligned over the years on a certain data format (bit order). through show how each signal should be connected from the graphic source through the SN65LVDS93B input, output and LVDS LCD panel input. Detailed notes are provided with each figure.



Note A. **FORMAT**: The majority of 24-bit LCD display panels require the two most significant bits (2 MSB) of each color to be transferred over the 4th serial data output Y3. A few 24-bit LCD display panels require the two LSBs of each color to be transmitted over the Y3 output. The system designer needs to verify which format is expected by checking the LCD display data sheet.

- Format 1: use with displays expecting the 2 MSB to be transmitted over the 4th data channel Y3. This is the dominate data format for LCD panels.
- Format 2: use with displays expecting the 2 LSB to be transmitted over the 4th data channel.

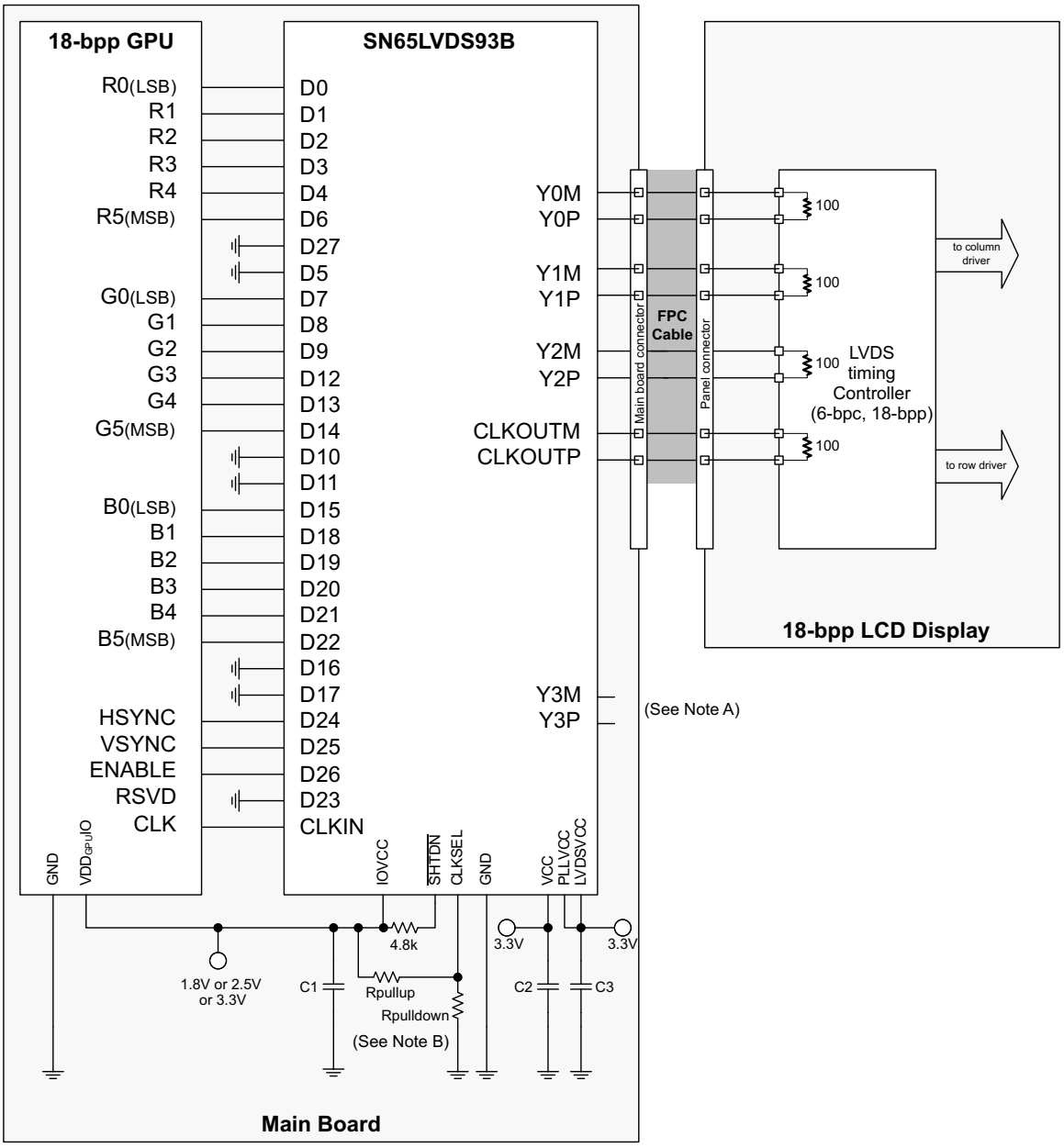
Note B. **Rpullup**: install only to use rising edge triggered clocking.
Rpulldown: install only to use falling edge triggered clocking.

- C1: decoupling capacitor for the VDDIO supply; install at least 1x0.01µF.
- C2: decoupling capacitor for the VDD supply; install at least 1x0.1µF and 1x0.01µF.
- C3: decoupling capacitor for the VDDPLL and VDDLVDS supply; install at least 1x0.1µF and 1x0.01µF.

Note C. If RSVD is not driven to a valid logic level, then an external connection to GND is recommended.

Note D. RSVD must be driven to a valid logic level. All unused SN65LVDS93B inputs must be tied to a valid logic level.

図 13. 24-Bit Color Host to 24-Bit LCD Panel Application

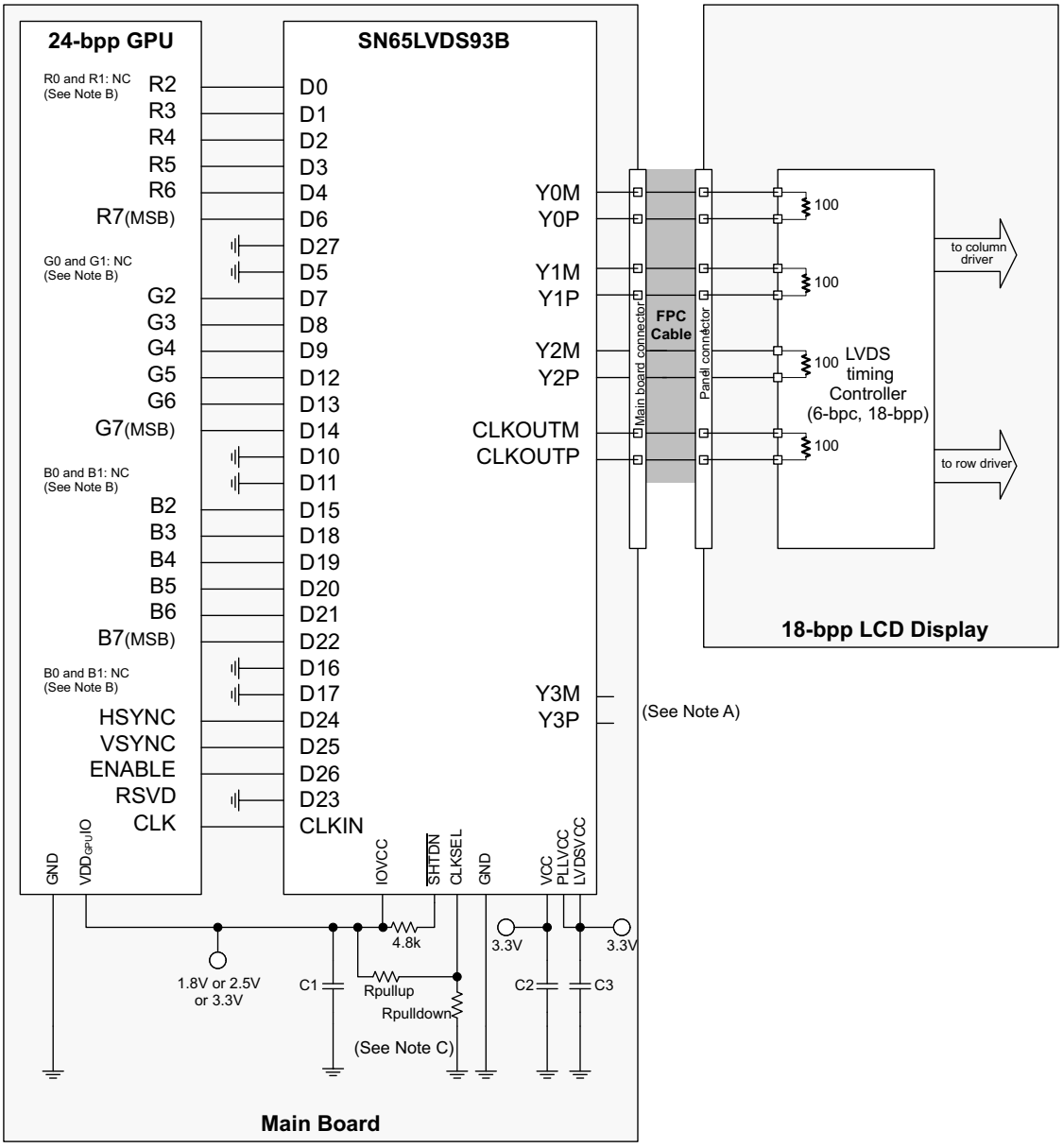


Note A. Leave output Y3 NC.

Note B.**Rpullup**: install only to use rising edge triggered clocking.
Rpulldown: install only to use falling edge triggered clocking.

- C1: decoupling capacitor for the VDDIO supply; install at least 1x0.01µF.
- C2: decoupling capacitor for the VDD supply; install at least 1x0.1µF and 1x0.01µF.
- C3: decoupling capacitor for the VDDPLL and VDDLVDS supply; install at least 1x0.1µF and 1x0.01µF.

図 14. 18-Bit Color Host to 18-Bit Color LCD Panel Display Application



Note A. Leave output Y3 NC.

Note B. **R0, R1, G0, G1, B0, B1**: For improved image quality, the GPU should dither the 24-bit output pixel down to18-bit per pixel.

NoteC.**Rpullup**: install only to use rising edge triggered clocking.
Rpulldown: install only to use falling edge triggered clocking.

- C1: decoupling capacitor for the VDDIO supply; install at least 1x0.01µF.
- C2: decoupling capacitor for the VDD supply; install at least 1x0.1µF and 1x0.01µF.
- C3: decoupling capacitor for the VDDPLL and VDDLVDS supply; install at least 1x0.1µF and 1x0.01µF.

図 15. 24-Bit Color Host to 18-Bit Color LCD Panel Display Application

10.2.2.3 PCB Routing

図 16 shows a possible breakout of the data input and output signals on two layers of a printed-circuit-board.

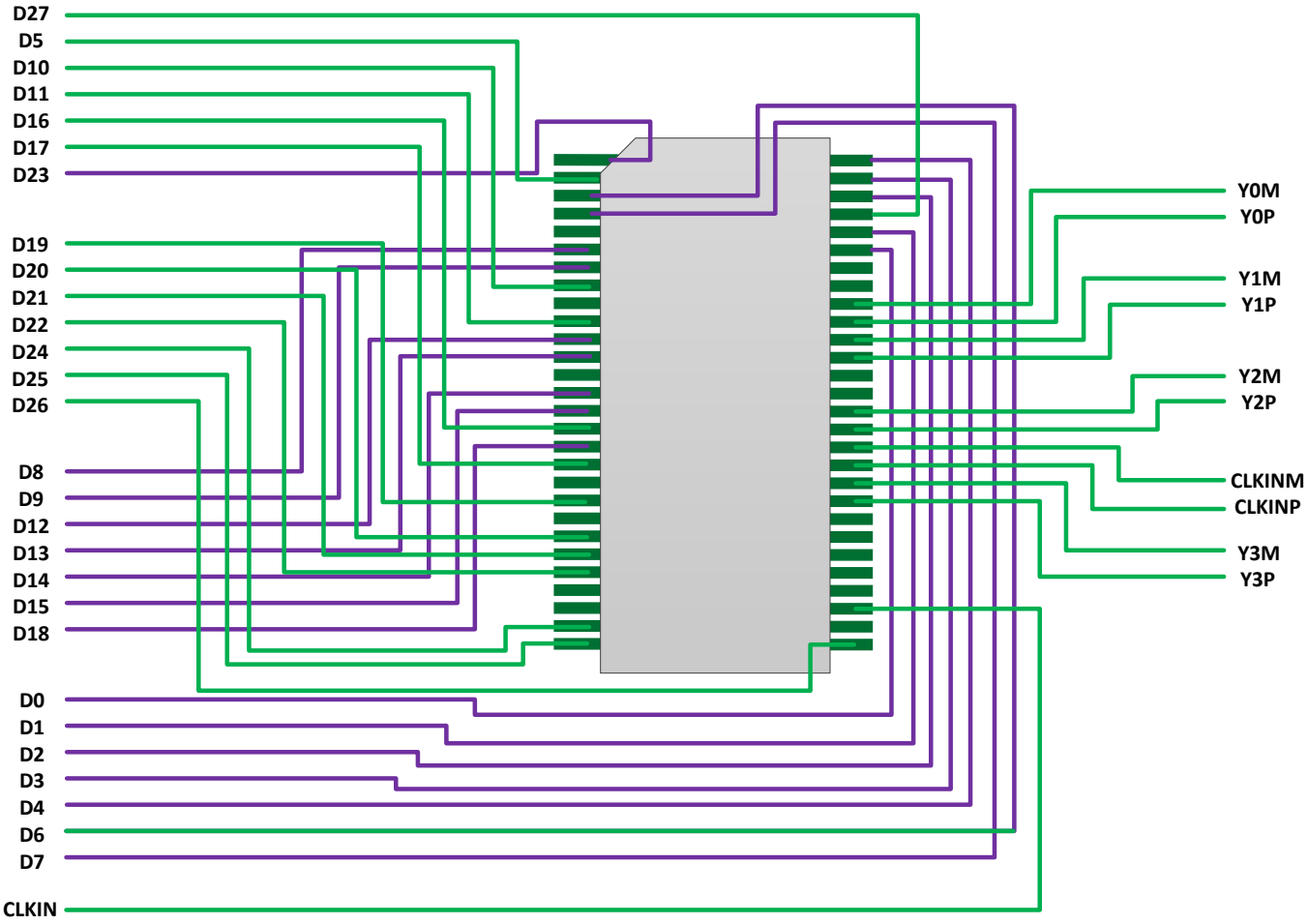


図 16. Printed-Circuit-Board Routing Example (See 図 12 for the Schematic)

10.2.3 Application Curve

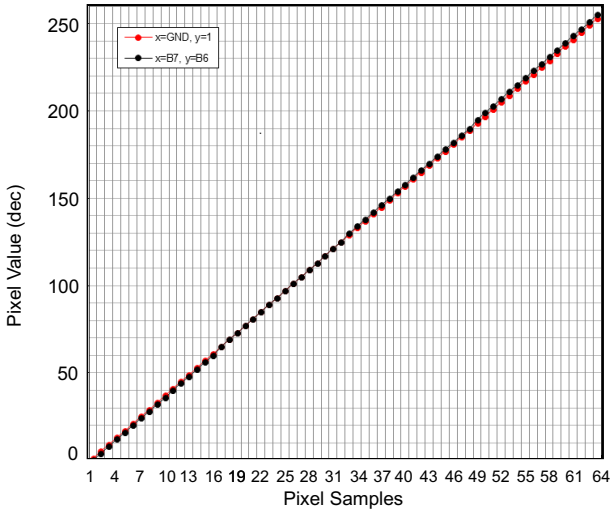


図 17. 18b GPU to 24b LCD

11 Power Supply Recommendations

Power supply PLL, IO, and LVDS pins must be uncoupled from each.

12 Layout

12.1 Layout Guidelines

12.1.1 Board Stackup

There is no fundamental information about how many layers should be used and how the board stackup should look. Again, the easiest way the get good results is to use the design from the EVMs of TI. The magazine *Elektronik Praxis* has published an article with an analysis of different board stackups. These are listed in 表 4. Generally, the use of microstrip traces needs at least two layers, whereas one of them must be a GND plane. Better is the use of a 4-layer PCB, with a GND and a VCC plane and two signal layers. If the circuit is complex and signals must be routed as stripline, because of propagation delay and/or characteristic impedance, a 6-layer stackup should be used.

表 4. Possible Board Stackup on a Four-Layer PCB

	MODEL 1	MODEL 2	MODEL 3	MODEL 4
Layer 1	SIG	SIG	SIG	GND
Layer 2	SIG	GND	GND	SIG
Layer 3	VCC	VCC	SIG	VCC
Layer 4	GND	SIG	VCC	SIG
Decoupling	Good	Good	Bad	Bad
EMC	Bad	Bad	Bad	Bad
Signal Integrity	Bad	Bad	Good	Bad
Self Disturbance	Satisfaction	Satisfaction	Satisfaction	High

12.1.2 Power and Ground Planes

A complete ground plane in high-speed design is essential. Additionally, a complete power plane is recommended as well. In a complex system, several regulated voltages can be present. The best solution is for every voltage to have its own layer and its own ground plane. But this would result in a huge number of layers just for ground and supply voltages. What are the alternatives? Split the ground planes and the power planes? In a mixed-signal design, for example, using data converters, the manufacturer often recommends splitting the analog ground and the digital ground to avoid noise coupling between the digital part and the sensitive analog part. Take care when using split ground planes because:

- Split ground planes act as slot antennas and radiate.
- A routed trace over a gap creates large loop areas, because the return current cannot flow beside the signal, and the signal can induce noise into the nonrelated reference plane (図 18).
- With a proper signal routing, crosstalk also can arise in the return current path due to discontinuities in the ground plane. Always take care of the return current (図 19).

For 図 19, do not route a signal referenced to digital ground over analog ground and vice versa. The return current cannot take the direct way along the signal trace and so a loop area occurs. Furthermore, the signal induces noise, due to crosstalk (dotted red line) into the analog ground plane.

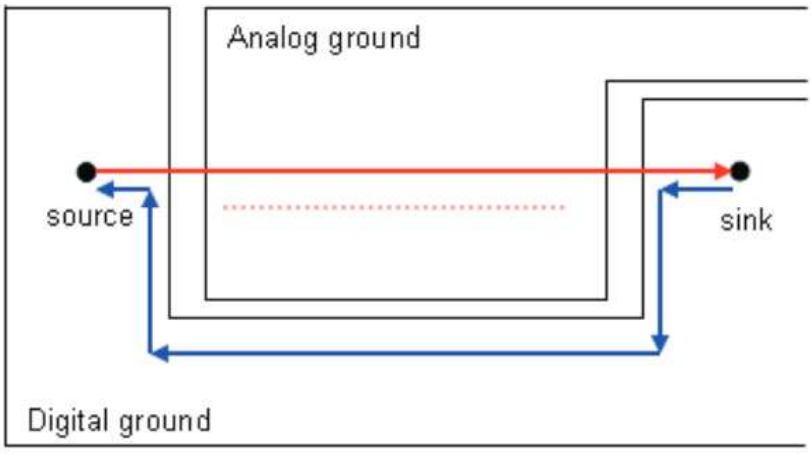


図 18. Loop Area and Crosstalk Due to Poor Signal Routing and Ground Splitting

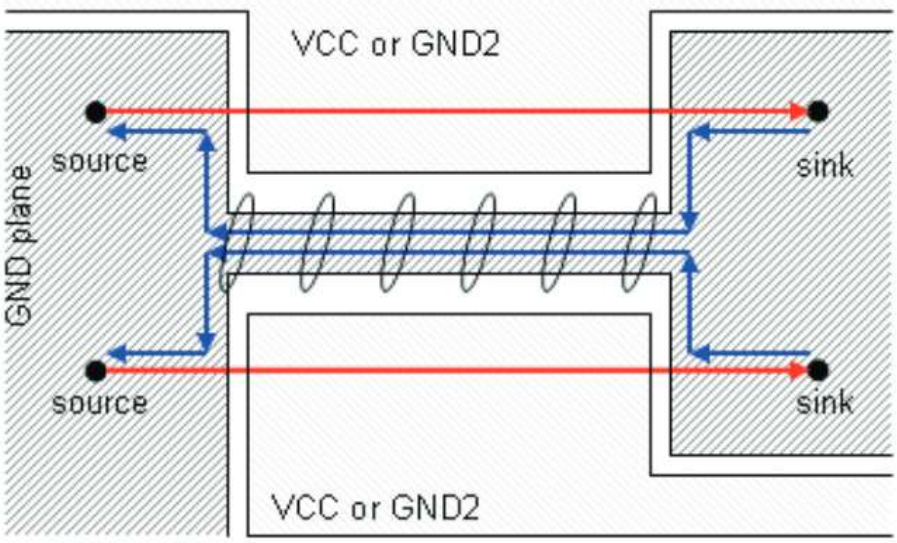


図 19. Crosstalk Induced by the Return Current Path

12.1.3 Traces, Vias, and Other PCB Components

A right angle in a trace can cause more radiation. The capacitance increases in the region of the corner, and the characteristic impedance changes. This impedance change causes reflections.

- Avoid right-angle bends in a trace and try to route them at least with two 45° corners. To minimize any impedance change, the best routing would be a round bend (see 図 20).
- Separate high-speed signals (for example, clock signals) from low-speed signals and digital from analog signals; again, placement is important.
- To minimize crosstalk not only between two signals on one layer but also between adjacent layers, route them with 90° to each other.

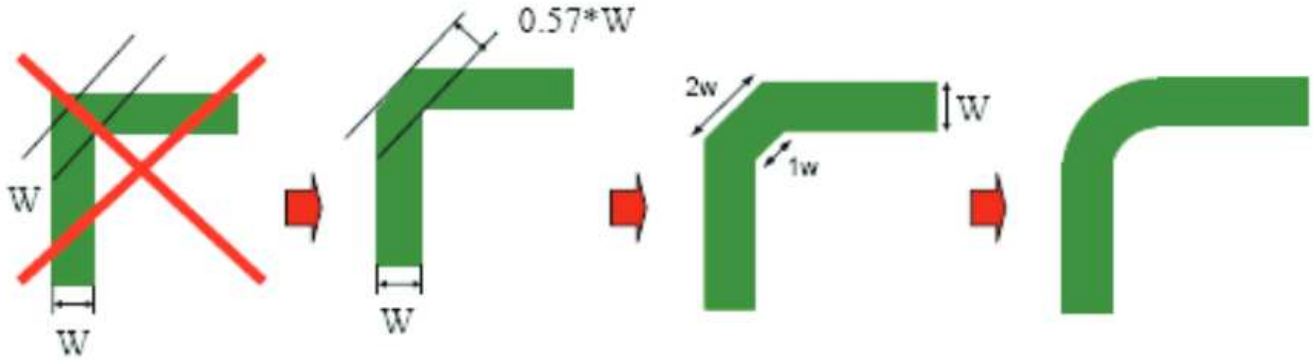


図 20. Poor and Good Right-Angle Bends

12.2 Layout Example

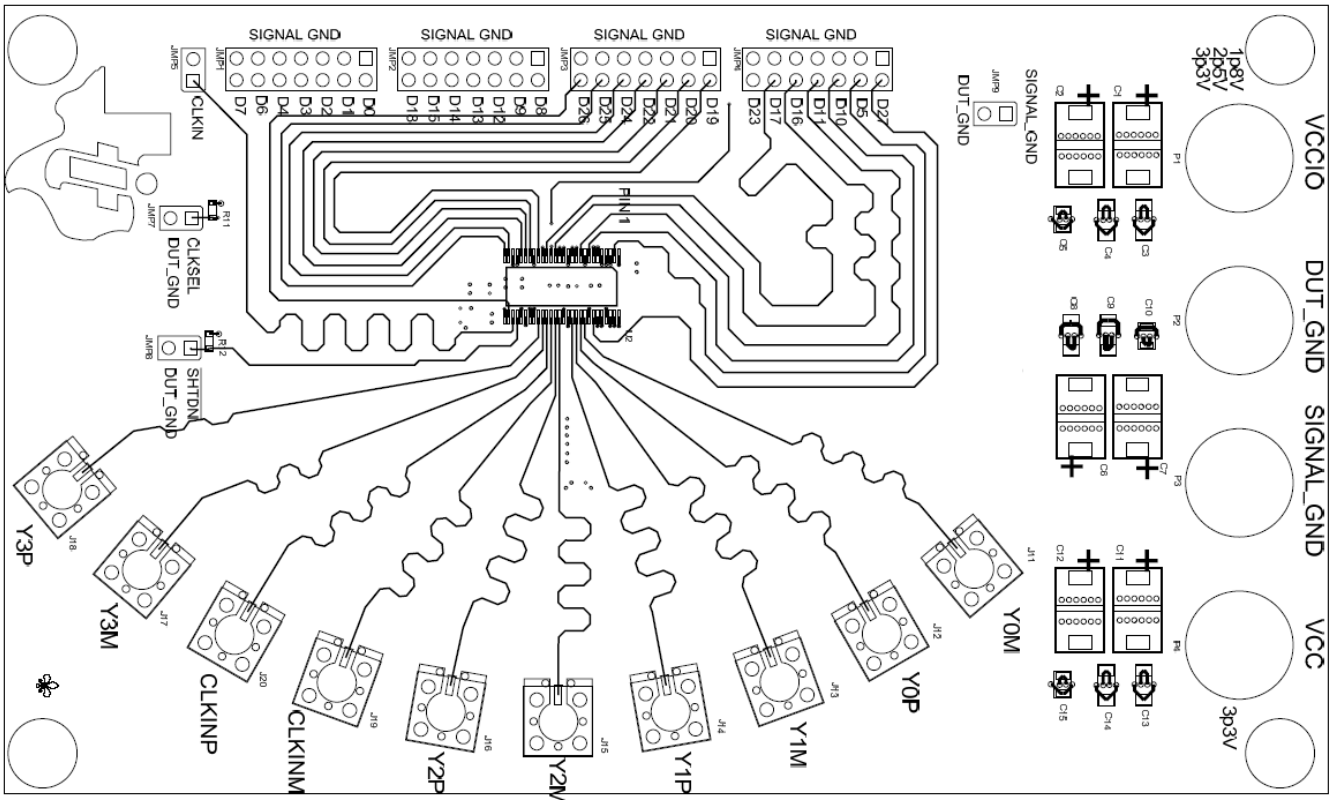


図 21. EVM Top Layer – TSSOP Package

Layout Example (continued)

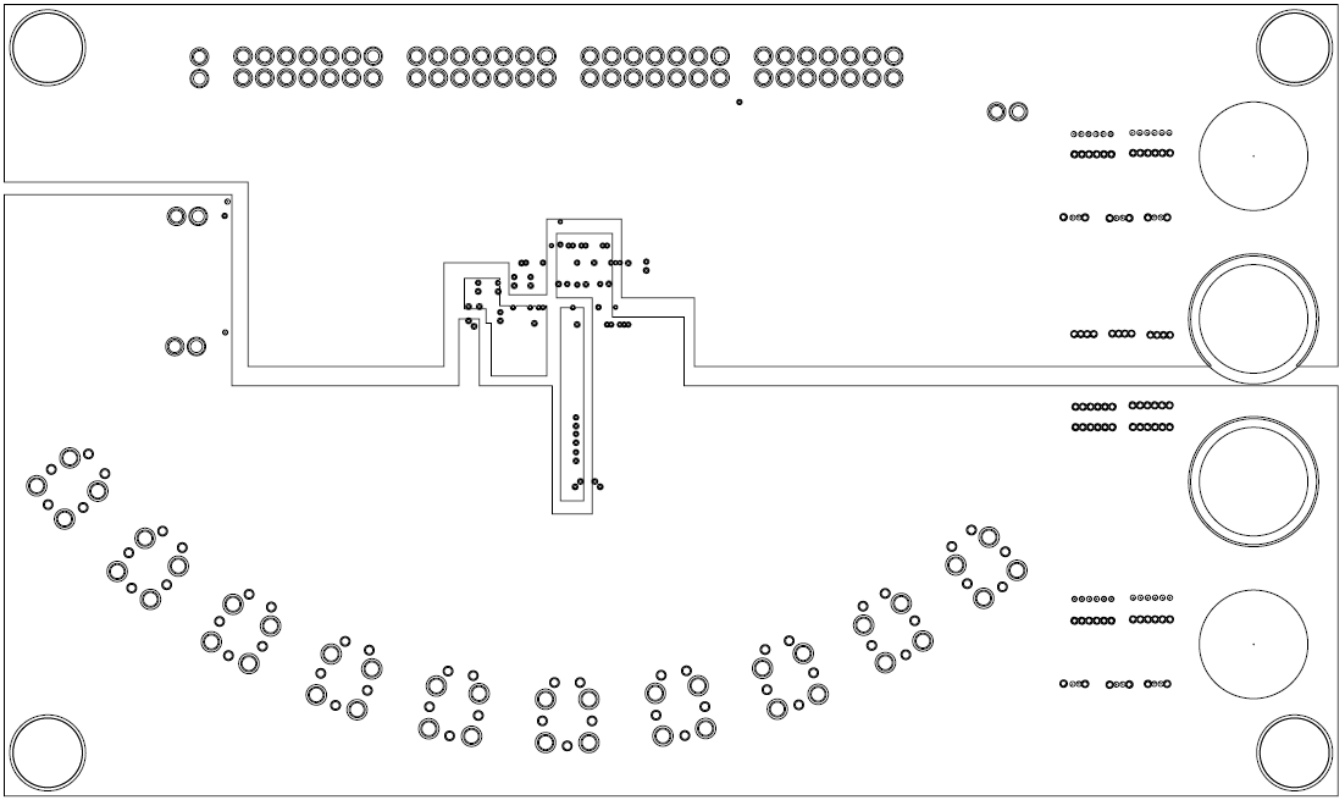


図 22. EVM VCC Layer – TSSOP Package

13 デバイスおよびドキュメントのサポート

13.1 ドキュメントのサポート

13.1.1 関連資料

関連資料については、以下を参照してください。

『*LVDS SerDesレシーバ*』、SNLS043H

13.2 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、ti.comのデバイス製品フォルダを開いてください。右上の隅にある「*通知を受け取る*」をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取れます。変更の詳細については、修正されたドキュメントに含まれている改訂履歴をご覧ください。

13.3 コミュニティ・リソース

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

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13.4 商標

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13.5 静電気放電に関する注意事項

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13.6 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

14 メカニカル、パッケージ、および注文情報

以降のページには、メカニカル、パッケージ、および注文に関する情報が記載されています。この情報は、そのデバイスについて利用可能な最新のデータです。このデータは予告なく変更されることがあり、ドキュメントが改訂される場合もあります。本データシートのブラウザ版を使用されている場合は、画面左側の説明をご覧ください。

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN65LVDS93BDGG	ACTIVE	TSSOP	DGG	56	35	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	LVDS93B	Samples
SN65LVDS93BDGGR	ACTIVE	TSSOP	DGG	56	2000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	LVDS93B	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

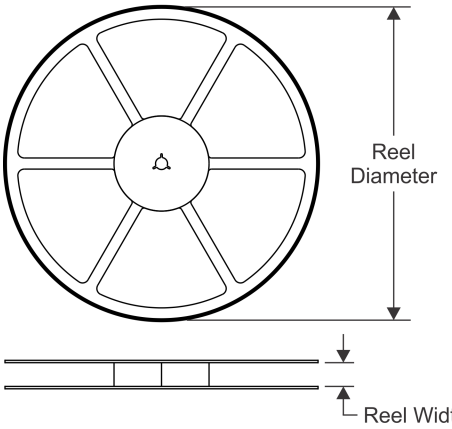
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

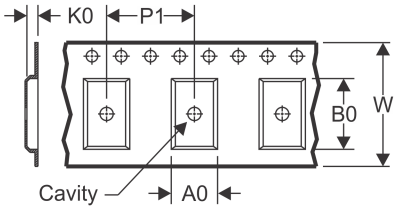
(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

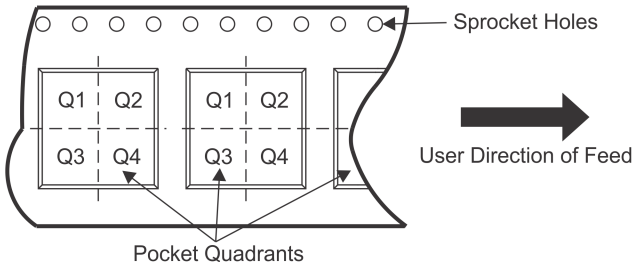


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

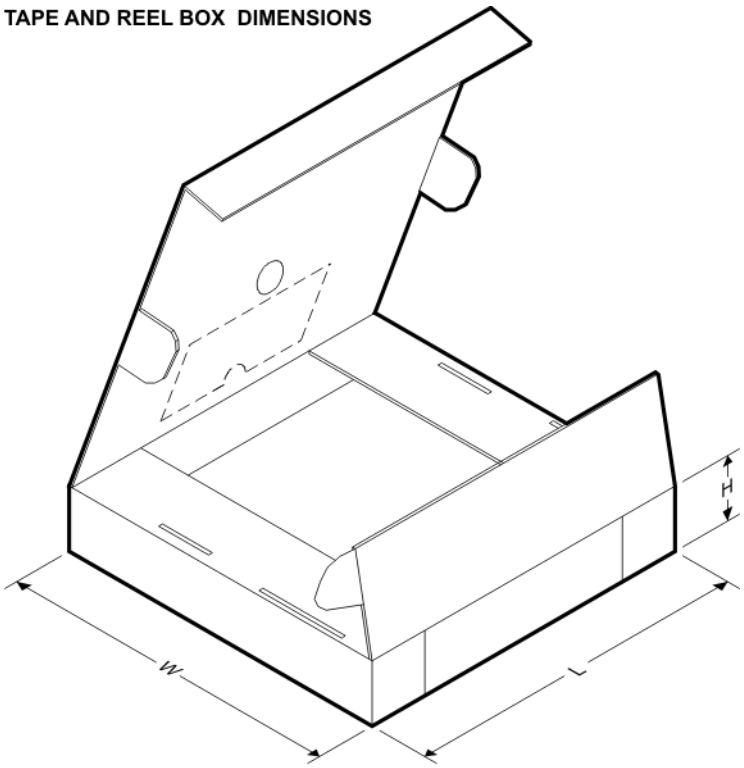
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65LVDS93BDGGR	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1

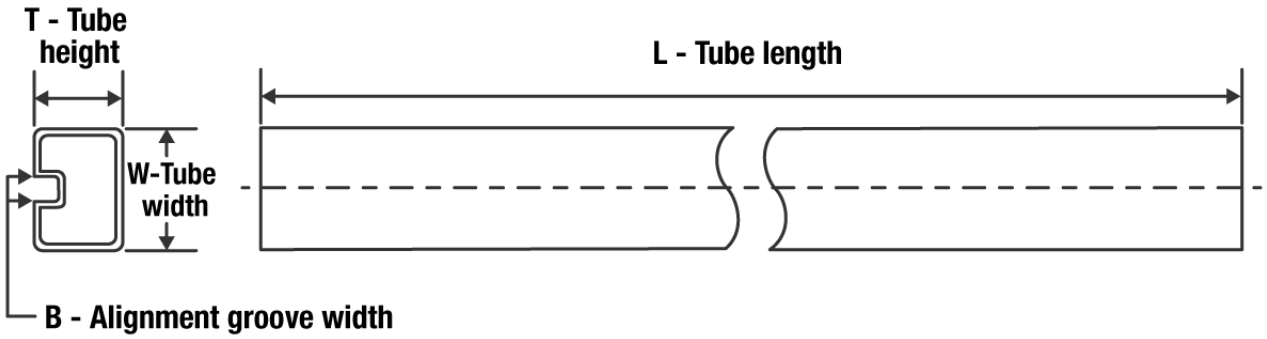
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN65LVDS93BDGGR	TSSOP	DGG	56	2000	367.0	367.0	45.0

TUBE



*All dimensions are nominal

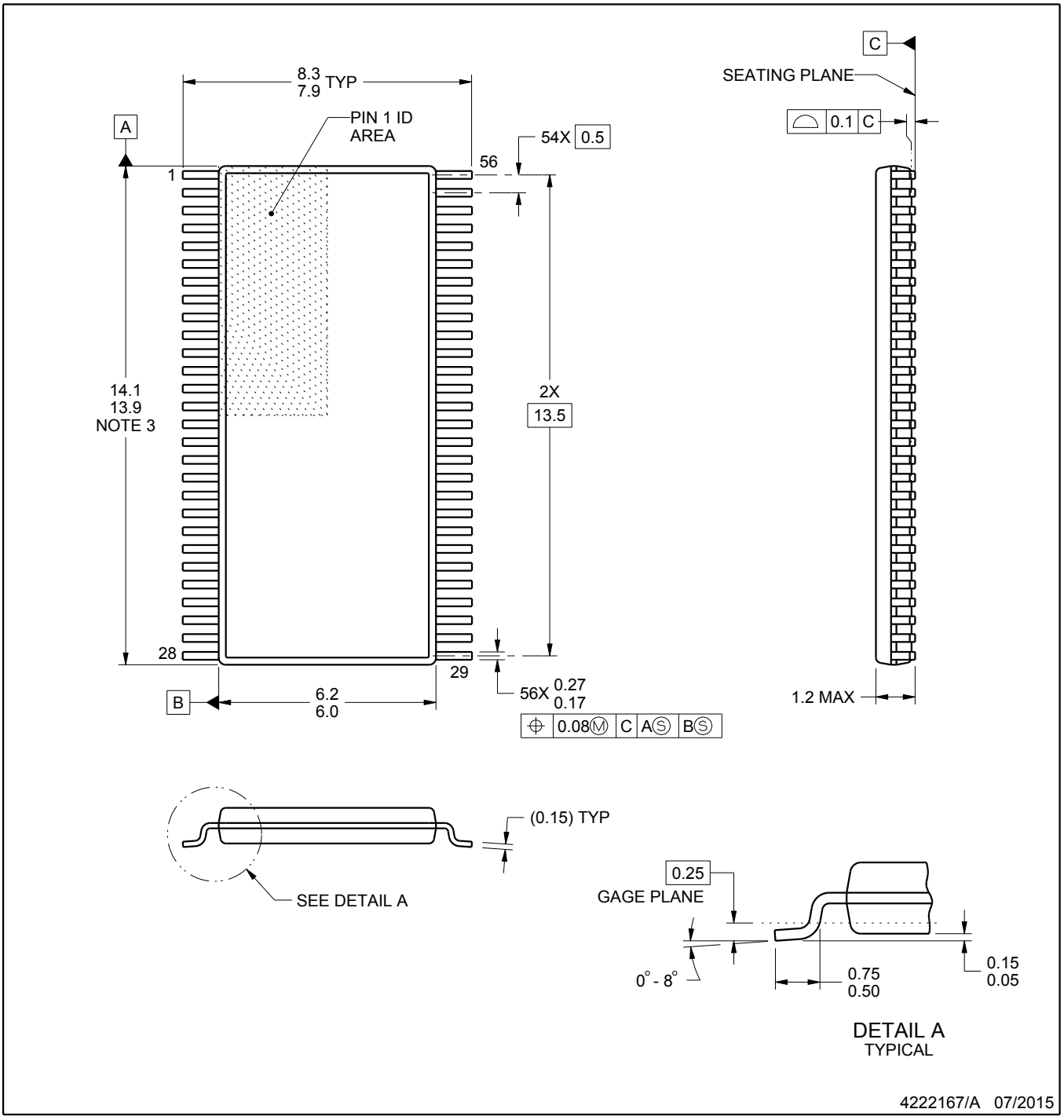
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN65LVDS93BDGG	DGG	TSSOP	56	35	530	11.89	3600	4.9

PACKAGE OUTLINE

DGG0056A

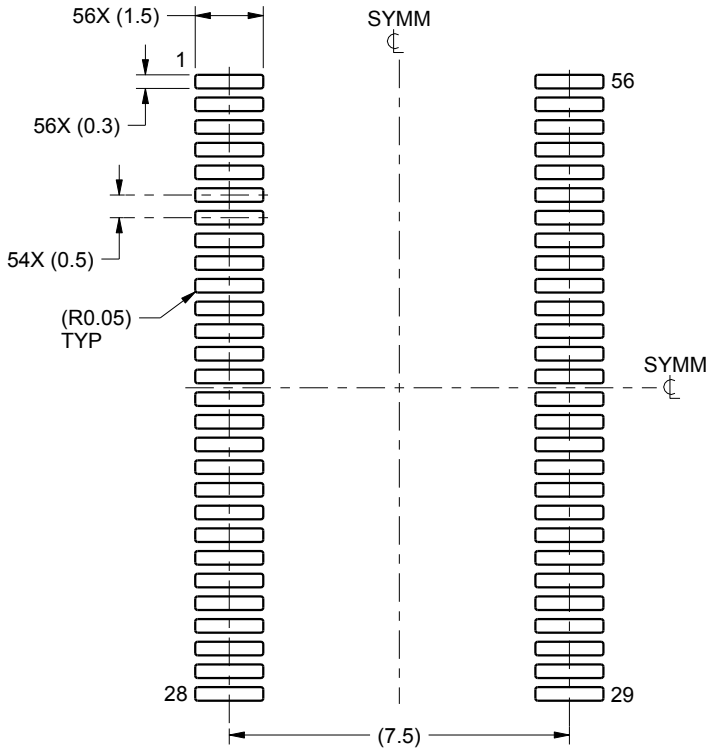
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

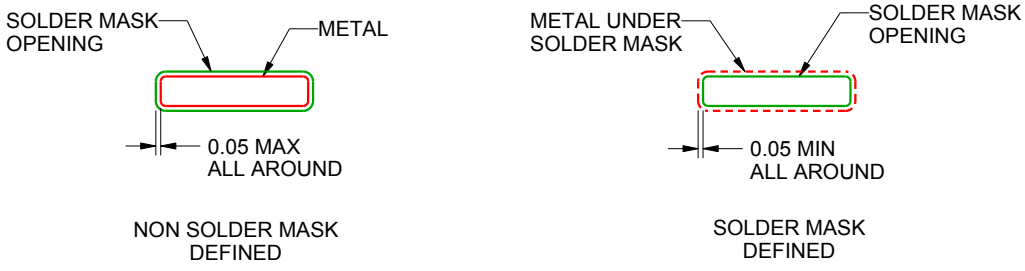


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-153.



LAND PATTERN EXAMPLE
SCALE:6X

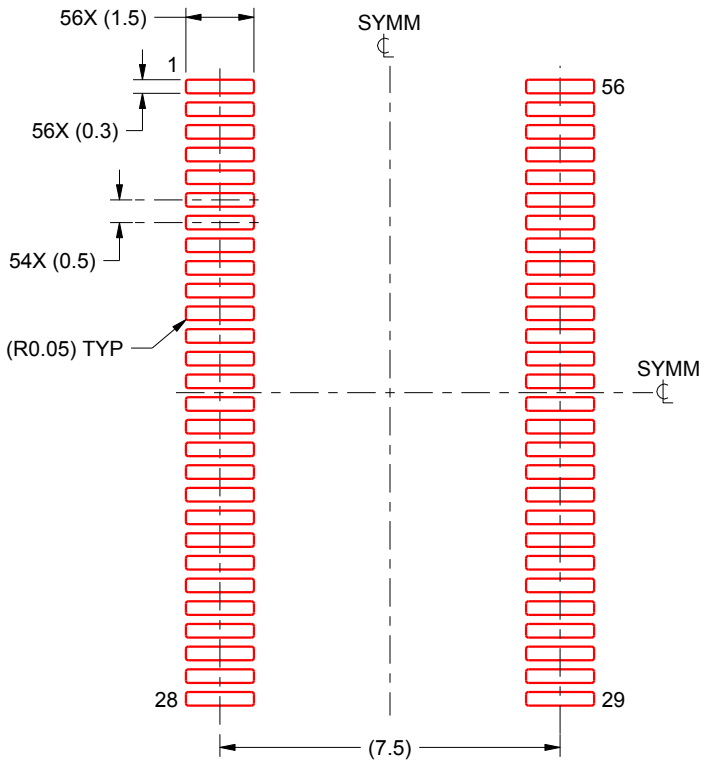


SOLDER MASK DETAILS

4222167/A 07/2015

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4222167/A 07/2015

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

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郵送先住所：Texas Instruments, Post Office Box 655303, Dallas, Texas 75265